

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	5.0	A
T_{OP}	Operating Temperature	-40 to 125	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

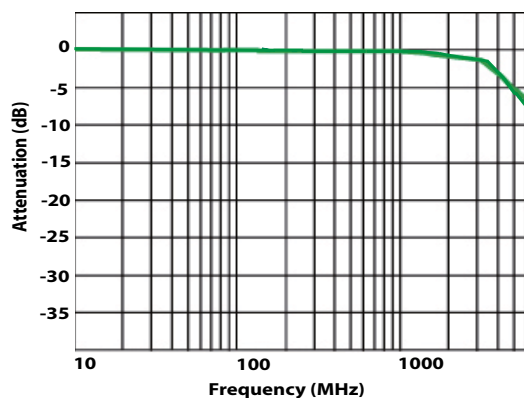
Electrical Characteristics ($T_{OP}=25^{\circ}C$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R=1\mu A$			5.0	V
Breakdown Voltage	V_{BR}	$I_R=1mA$	6.0			V
Reverse Leakage Current	I_{LEAK}	$V_R=5V$			1	μA
Clamp Voltage ¹	V_C	$I_{PP}=1A, t_p=8/20\mu s, I/O$ to GND		6.9		V
		$I_{PP}=2A, t_p=8/20\mu s, I/O$ to GND		7.5		V
Dynamic Resistance ²	R_{DYN}	TLP, $t_p=100ns, I/O$ to GND		0.6		Ω
ESD Withstand Voltage ¹	V_{ESD}	IEC 61000-4-2 (Contact)	± 10			kV
		IEC 61000-4-2 (Air)	± 15			kV
Diode Capacitance ¹	$C_{I/O-I/O}$	Reverse Bias=0V, $f=1$ MHz		0.8		pF

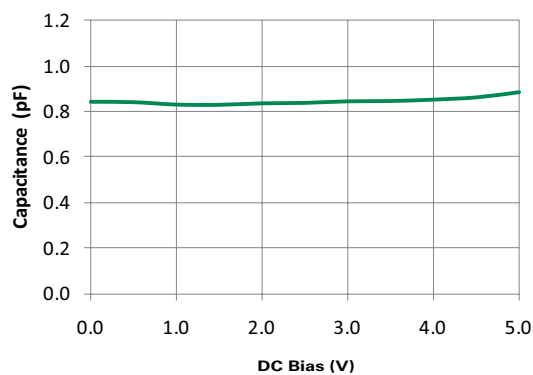
Note: 1. Parameter is guaranteed by design and/or component characterization.

2. Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window $t_1=70ns$ to $t_2=90ns$

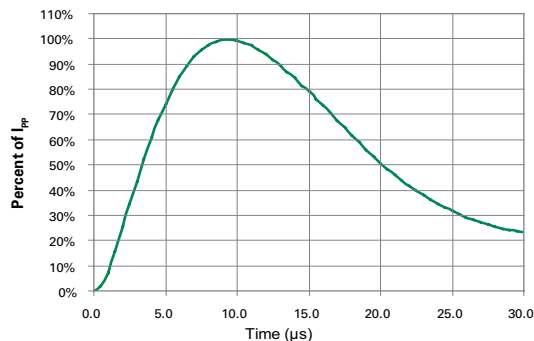
Insertion Loss (S21) I/O to GND



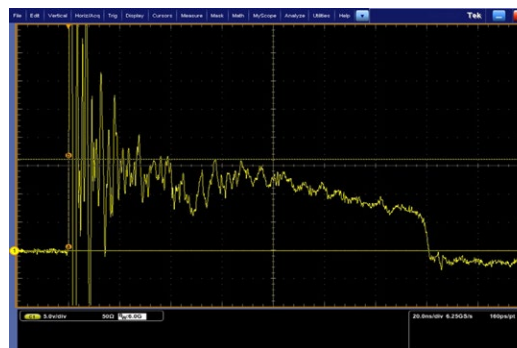
Capacitance vs. Reverse Voltage



8/20μs Waveform



8kV Clamping Voltage



Product Characteristics

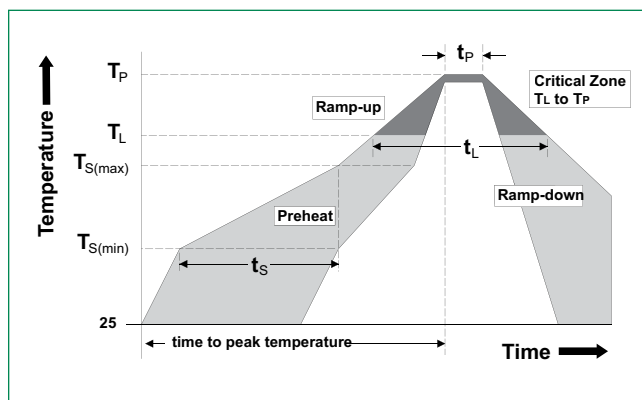
Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Substitute Material	Silicon
Body Material	Molded Compound
Flammability	UL Recognized compound meeting flammability rating V-0

Ordering Information

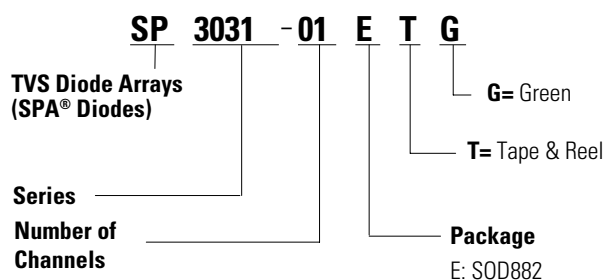
Part Number	Package	Min. Order Qty.
SP3031-01ETG	SOD882	10000

Soldering Parameters

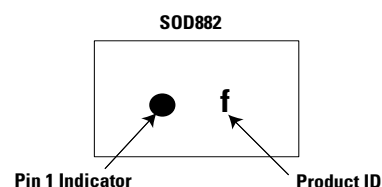
Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



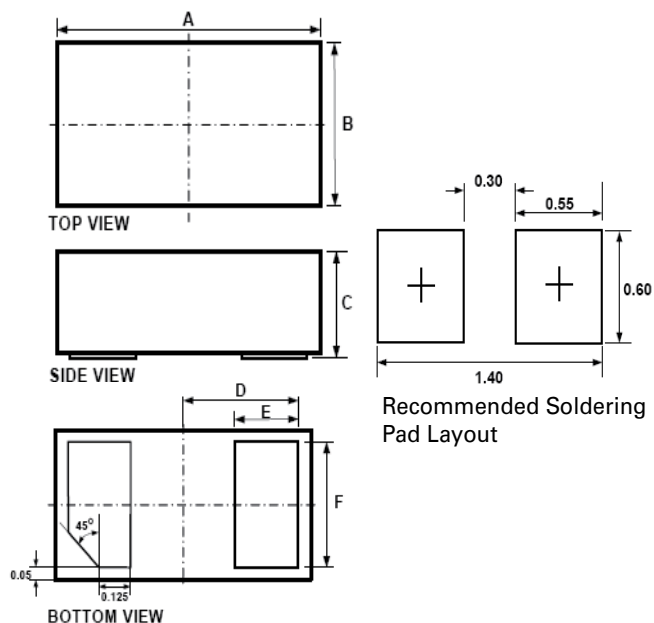
Part Numbering System



Part Marking System

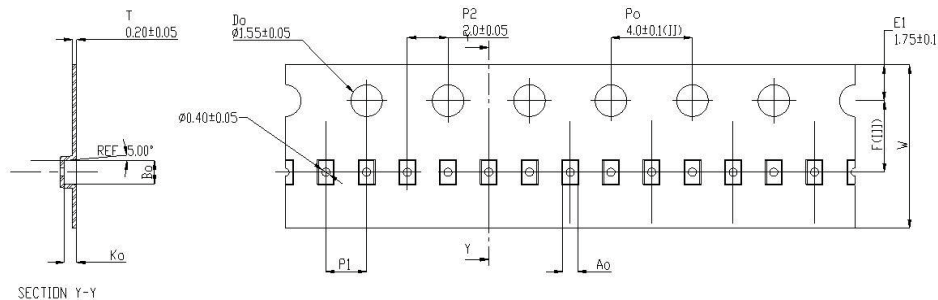


Package Dimensions — SOD882



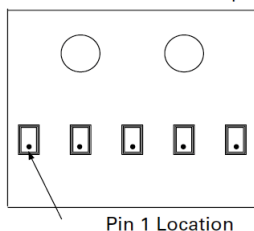
Symbol	Package	SOD882				
	JEDEC	MO-236				
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.90	1.00	1.10	0.035	0.039	0.043
B	0.50	0.60	0.70	0.020	0.024	0.028
C	0.40	0.50	0.60	0.016	0.020	0.024
D	0.45			0.018		
E	0.20	0.25	0.35	0.008	0.010	0.012
F	0.45	0.50	0.55	0.018	0.020	0.022

Embossed Carrier Tape & Reel Specification — SOD882



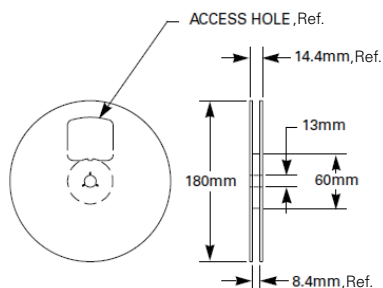
Symbol	Millimeters
A0	0.70±0.045
B0	1.10±0.045
K0	0.65±0.045
F	3.50±0.05
P1	2.00±0.10
W	8.00 + 0.30 -0.10

Device Orientation in Tape



Notes:
1. All dimensions are in millimeters

8mm TAPE AND REEL



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